

[0019] FIG. 4g illustrates a view of the magnetoresistive sensor undergoing oxygen reactive ion etching; and,

[0020] FIG. 4h illustrates a view of the completed magnetoresistive sensor.

DETAILED DESCRIPTION OF THE INVENTION

[0021] A magnetoresistive sensor having antiparallel coupled biasing tabs according to a preferred embodiment of the invention includes a protective cap layer for each biasing tab. A sensor according to the invention has low parasitic resistance. During manufacture, a sensor having a bias tab structure according to the invention is effectively protected from damage due to ion milling.

[0022] Referring to FIG. 1, a magnetic disk drive 100 has at least one rotatable magnetic disk 102 supported by a spindle 104 and rotated by a motor (not shown). There is at least one slider 106 with an attached recording head 108 positioned over the disk 102 surface while reading and writing. The recording head 108 includes a write element for writing data onto the disk 102. The recording head also includes a magnetic spin valve sensor according to the present invention (shown in detail below) used as a read element for reading data from the disk. The slider 106 is attached to a suspension 110 and the suspension 110 is attached to an actuator 112. The actuator 112 is pivotally attached 114 to the housing 116 of the disk drive 100 and is pivoted by a voice coil motor 118. As the disk is rotating, the actuator 112 positions the slider 106 and suspension 110 along a radial arcuate path 120 over the disk 102 surface to access the data track of interest.

[0023] Again referring to FIG. 1, during operation of the disk drive 100, the motion of the rotating disk 102 relative to the slider 106 generates an air bearing between the slider 106 and the disk 102 surface which exerts an upward force on the slider 106. This upward force is balanced by a spring force from the suspension 110 urging the slider 106 toward the surface of the disk 102. Alternatively, the slider 106 may be in either partial or continuous contact with the disk 102 surface during operation.

[0024] FIG. 2 illustrates a more detailed view of a slider 200. The recording head 218 is preferably constructed on the trailing surface 206 of the slider 200. FIG. 2 illustrates the upper pole 208 and the turns 210 of the coil 214 of the write element of the recording head 218. The read element includes a read sensor 204 disposed between two magnetic shields 220 is formed between the slider body 202 and the write element. The electrical connection pads 212 which allow connection with the write element and read element are illustrated.

[0025] FIG. 3a illustrates a partially completed magnetoresistive sensor 300 according to the prior art. The pinned layer 302 may be a simple layer of ferromagnetic material. Alternatively, the pinned layer 302 may be an assembly of antiparallel coupled ferromagnetic layers. The pinned layer 302 may be formed over an antiferromagnetic layer (not shown). Alternatively, a antiferromagnetic layer may not be necessary if the pinned layer 302 is self-pinned. A nonmagnetic conducting layer 304 is formed over the pinned layer 302. A ferromagnetic free layer 306 is formed over the nonmagnetic conducting layer 304. A thin nonmagnetic

layer 308, usually ruthenium, is formed over the free layer 306 and promotes antiparallel coupling with the ferromagnetic bias layer 310 which is formed over the thin nonmagnetic layer 308. A cap layer 312, usually of tantalum, is formed over the bias layer 310. The structure 300 as illustrated in FIG. 3a is now removed from vacuum and annealed at elevated temperature.

[0026] FIG. 3b illustrates a formation of oxidized material 314 in the cap layer 312 which resulted from the annealing operation. The oxide layer 314 must be removed with ion milling 316 to insure good electrical connection with subsequently formed lead structures (not shown). This ion milling operation 316 must be relatively aggressive to adequately remove the oxide layer 314 thus risking damage to the bias layer 310 and necessitating a thicker cap layer 312.

[0027] FIG. 4a illustrates a view of a partially completed magnetoresistive sensor 400 according to the present invention. The sensor 400 includes a pinned layer 402 which may be a simple layer of ferromagnetic material. Alternatively, the pinned layer 402 may be an assembly of antiparallel coupled ferromagnetic layers. The pinned layer 402 may be formed over an antiferromagnetic layer (not shown). Alternatively, an antiferromagnetic layer may not be necessary if the pinned layer 402 is self-pinned. A nonmagnetic conducting layer 404, typically of copper, is formed over the pinned layer 402. A ferromagnetic free layer 406 is formed over the nonmagnetic conducting layer 404. The free layer 406 may be a single layer of ferromagnetic alloy or alternatively multiple layers of ferromagnetic alloys. Appropriate ferromagnetic alloys are typically formed from binary or tertiary combinations of iron, nickel, and cobalt. A thin nonmagnetic coupling layer 408, usually ruthenium, is formed over the free layer 406. This thin nonmagnetic coupling layer 408 promotes antiparallel coupling between a ferromagnetic bias layer 410 formed over the thin nonmagnetic layer 408 and the underlying free layer 404. The magnetic moment of the bias layer 410 should ordinarily be somewhat greater than the magnetic moment of the free layer 406. A cap layer 412, usually of tantalum, is formed over the bias layer 410. Importantly, a protective cap layer 414 is formed over the cap layer 412. The protective cap layer 414 may be formed from rhodium (Rh), gold (Au), ruthenium (Ru), or other material which protects the cap layer against oxidation and is not readily oxidized itself. The protective cap layer 414 is effective in a thickness range of about 10 to 30 Angstroms. A protective cap layer thicker than 30 Angstroms is also likely to be effective but could add undesirable thickness to the sensor stack. The magnetoresistive sensor 400 as illustrated in FIG. 4a is now removed from vacuum and annealed at elevated temperature.

[0028] FIG. 4b illustrates a view of the magnetoresistive sensor after annealing and after the formation of a photoresist liftoff structure 450. The cap layer 412 was protected from oxidation during annealing by the protective cap layer 414. The material chosen for the protective cap layer 414 is not readily oxidized during annealing. An advantage of the present invention is that the cap layer can be relatively thin with a thickness range of about 30 to 50 Angstroms. In contrast, the thickness of the cap layer of the prior art (312 in FIGS. 3a and 3b) was typically greater than about 80 Angstroms.